DS92LV1021 and DS92LV1210 16-40 MHz 10 Bit Bus LVDS Serializer and Deserializer

Check for Samples: DS92LV1021, DS92LV1210

FEATURES

- **Ensured Transition Every Data Transfer Cycle**
- **Single Differential Pair Eliminates Multi-channel Skew**
- **Flow-through Pinout for Easy PCB Layout**
- **400 Mbps Serial Bus LVDS Bandwidth (at 40 MHz clock)**
- **10-bit Parallel Interface for 1 Byte Data Plus 2 Control Bits**
- **Synchronization Mode and LOCK Indicator**
- **Programmable Edge Trigger on Clock**
- **High Impedance on Receiver Inputs When Power is off**
- **Bus LVDS Serial Output Rated for 27Ω Load**
- **Small 28-lead SSOP Package (DB)**

DESCRIPTION

The DS92LV1021 transforms a 10-bit wide parallel CMOS/TTL data bus into a single high speed Bus LVDS serial data stream with embedded clock. The DS92LV1210 receives the Bus LVDS serial data stream and transforms it back into a 10-bit wide parallel data bus and separates clock. The DS92LV1021 may transmit data over heavily loaded backplanes or 10 meters of cable. The reduced cable, PCB trace count and connector size saves cost and makes PCB design layout easier. Clock-to-data and data-to-data skew are eliminated since one output will transmit both clock and all data bits serially. The powerdown pin is used to save power, by reducing supply current when either device is not in use. The Serializer has a synchronization mode that should be activated upon power-up of the device. The Deserializer will establish lock to this signal within 1024 cycles, and will flag Lock status. The embedded clock ensures a transition on the bus every 12-bit cycle; eliminating transmission errors due to charged cable conditions. The DS92LV1021 output pins may be TRI-STATE to achieve a high impedance state. The PLL can lock to frequencies between 16 MHz and 40 MHz.

Block Diagram
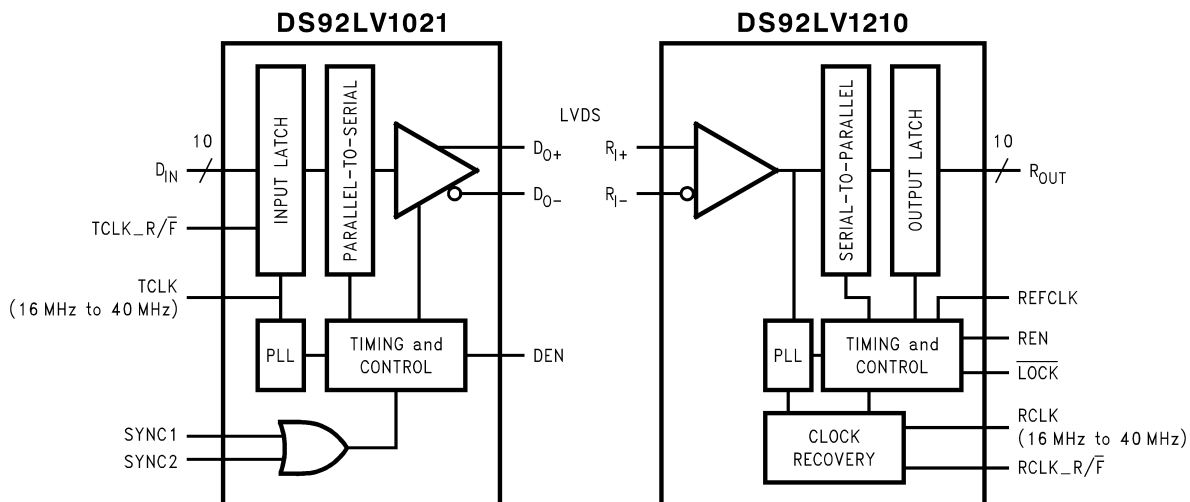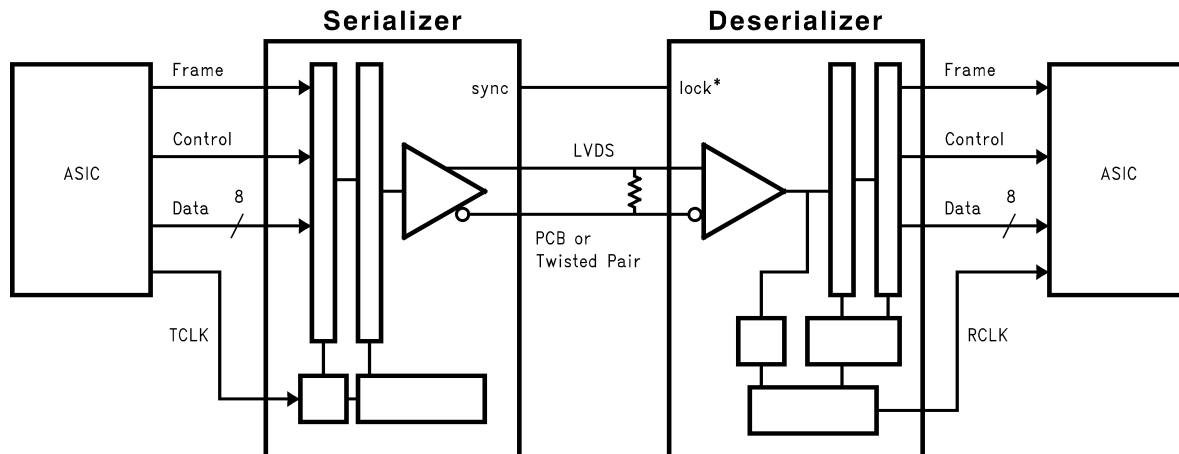
Figure 1. Application

Functional Description

The DS92LV1021 and DS92LV1210 is a 10-bit Serializer / Deserializer chipset designed to transmit data over a heavily loaded differential backplanes at clock speeds from 16 to 40MHz. It may also be used to drive data over Unshielded Twisted Pair (UTP) cable.

The chipset has three active states of operation: Initialization, Data Transfer, and Resynchronization; and two passive states: Powerdown and TRI-STATE.

The following sections describe each operation and passive state.

Initialization

Before data can be transferred both devices must be initialized. Initialization refers to synchronization of the Serializer and the Deserializer PLL's to local clocks that may be the same or separate. Afterward, synchronization of Deserializer to Serializer occurs as the second step of initialization.

Step 1: When V_{CC} is applied to both Serializer and/or Deserializer, the respective outputs are held in TRI-STATE and internal circuitry is disabled by on-chip power-on circuitry. When V_{CC} reaches V_{CC} OK (2.5V) the PLL in each device begins locking to a local clock. For the Serializer, the local clock is the transmit clock, TCLK, provided by the source ASIC or other device. For the Deserializer, the local clock is provided by an on-board oscillator or other source and applied to the REFCLK pin. After V_{CC} OK is reached the device's PLL will lock.

The Serializer outputs are held in TRI-STATE while the PLL locks to the TCLK. The Serializer is now ready to send data or SYNC patterns depending on the levels of the SYNC1 and SYNC2 inputs. The SYNC pattern is composed of six ones and six zeros switching at the input clock rate.

The Deserializer $\overline{\text{LOCK}}$ output will remain high while its PLL is locking to the local clock- the REFCLK input and then to SYNC patterns on the input.

Step 2: The Deserializer PLL must synchronize to the Serializer to complete the initialization. The transmission of SYNC patterns to the Deserializer enables the Deserializer to lock to the Serializer signal.

Control of the sync pins is left to the user. A feedback loop between the $\overline{\text{LOCK}}$ pin is one recommendation. Another option is that one or both of the Serializer SYNC inputs are asserted for at least 1024 cycles of TCLK to initiate transmission of SYNC patterns. The Serializer will continue to send SYNC patterns after the minimum of 1024 if either of the SYNC inputs remain high.

When the Deserializer detects edge transitions at the Bus LVDS input it will attempt to lock to the embedded clock information. When the Deserializer locks to the Bus LVDS clock, the $\overline{\text{LOCK}}$ output will go low. When $\overline{\text{LOCK}}$ is low the Deserializer outputs represent incoming Bus LVDS data.

Product Folder Links: *DS92LV1021 DS92LV1210*

Data Transfer

After initialization, the Serializer inputs DIN0–DIN9 may be used to input data to the Serializer. Data is clocked into the Serializer by the TCLK input. The edge of TCLK used to strobe in data is selectable via the TCLK_R/$\overline{F}$ pin. TCLK_R/$\overline{F}$ high selects the rising edge for clocking data and low selects the falling edge. If either of the SYNC inputs is high for 5*TCLK cycles the data at DIN 0-DIN9 is ignored regardless of the clock edge.

A start bit and a stop bit, appended internally, frame the data bits in the register. The start bit is always high and the stop bit is always low. The start and stop bits function as the embedded clock bits in the serial stream.

Serialized data and clock bits (10+2 bits) are transmitted from the serial data output (DO) at 12 times the TCLK frequency. For example, if TCLK is 40 MHz, the serial rate is 40 × 12 = 480 Mega bits per second. Since only 10 bits are from input data, the serial "payload" rate is 10 times the TCLK frequency. For instance, if TCLK = 40 MHz, the payload data rate is 40 × 10 = 400 Mbps. TCLK is provided by the data source and must be in the range 16 MHz to 40 MHz nominal.

The outputs (DO±) can drive a heavily loaded backplane or a point-to-point connection. The outputs transmit data when the enable pin (DEN) is high, PWRDN = high and SYNC1 and SYNC2 are low. The DEN pin may be used to TRI-STATE the outputs when driven low.

The $\overline{LOCK}$ pin on the Deserializer is driven low when it is synchronized with the Serializer. The Deserializer locks to the embedded clock and uses it to recover the serialized data. ROUT data is valid when $\overline{LOCK}$ is low. Otherwise ROUT0–ROUT9 is invalid.

RCLK pin is the reference to data on the ROUT0-ROUT9 pins. The polarity of the RCLK edge is controlled by the RCLK_R/$\overline{F}$ input.

ROUT(0-9), $\overline{LOCK}$ and RCLK outputs will drive a minimum of three CMOS input gates (15 pF load) with 40 MHz clock.

Resynchronization

The Deserializer $\overline{LOCK}$ pin driven low indicates that the Deserializer PLL is locked to the embedded clock edge. If the Deserializer loses lock, the $\overline{LOCK}$ output will go high and the outputs (including RCLK) will be TRI-STATE.

The $\overline{LOCK}$ pin must be monitored by the system to detect a loss of synchronization and the system must arrange to pulse the Serializer SYNC1 or SYNC2 pin to resynchronize. There are multiple approaches possible. One recommendation is to provide a feedback loop using the $\overline{LOCK}$ pin itself to control the sync request of the Serializer (SYNC1 or SYNC2). Otherwise, $\overline{LOCK}$ pin needs to be monitored and when it is a high, the system needs to ensure that one or both of the Serializer SYNC inputs area asserted for at least 1024 cycles of TCLK. A minimum of 1024 sync patterns are needed to resynchronize. Dual SYNC pins are provided for multiple control in a multi-drop application.

Powerdown

The Powerdown state is a low power sleep mode that the Serializer and Deserializer may use to reduce power when there is no data to be transferred. Powerdown is entered when $\overline{PWRDN}$ and REN are driven low on the Deserializer, and when the PWRDN is driven low on the Serializer. In Powerdown, the PLL is stopped and the outputs go into TRI-STATE, disabling load current and also reducing supply current to the milliamp range. To exit Powerdown, PWRDN is driven high.

Both the Serializer and Deserializer must reinitialize and resynchronize before data can be transferred. Initialization of the Serializer takes 1024 TCLK cycles. The Deserializer will initialize and assert $\overline{LOCK}$ high until it is locked to the Bus LVDS clock.

TRI-STATE

For the Serializer, TRI-STATE is entered when the DEN pin is driven low. This will TRI-STATE both driver output pins (DO+ and DO−). When DEN is driven high the serializer will return to the previous state as long as all other control pins remain static (SYNC1, SYNC2, $\overline{PWRDN}$, TCLK_R/$\overline{F}$).

For the Deserializer, TRI-STATE is entered when the REN pin is driven low. This will TRI-STATE the receiver output pins (ROUT0–ROUT9), $\overline{LOCK}$ and RCLK.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings [1][2]

Supply Voltage (V_{CC})	−0.3V to +4V
CMOS/TTL Input Voltage	−0.3V to (V_{CC} +0.3V)
CMOS/TTL Output Voltage	−0.3V to (V_{CC} +0.3V)
Bus LVDS Receiver Input Voltage	−0.3V to +3.9V
Bus LVDS Driver Output Voltage	−0.3V to +3.9V
Bus LVDS Output Short Circuit Duration	Continuous
Junction Temperature	+150°C
Storage Temperature	−65°C to +150°C
Lead Temperature	
(Soldering, 4 seconds)	+260°C
Maximum Package Power Dissipation Capacity	
@ 25°C Package: 28L SSOP	1.27 W
Package Derating:	
28L SSOP	10.2 mW/°C above +25°C
ESD Rating (HBM)	>5kV

(1) "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be verified. They are not meant to imply that the devices should be operated at these limits. The table of "Electrical Characteristics" specifies conditions of device operation.
(2) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.

Recommended Operating Conditions

	Min	Nom	Max	Units
Supply Voltage (V_{CC})	3.0	3.3	3.6	V
Operating Free Air Temperature (T_A)	−40	+25	+85	°C
Receiver Input Range	0		2.4	V
Supply Noise Voltage (V_{CC})				100 mV$_{P-P}$

Electrical Characteristics[1]

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[2]	Max	Units
SERIALIZER CMOS/TTL DC SPECIFICATIONS (apply to DIN0-9, TCLK, $\overline{PWRDN}$, TCLK_R/$\overline{F}$, SYNC1, SYNC2, DEN)						
V_{IH}	High Level Input Voltage		2.0		V_{CC}	V
V_{IL}	Low Level Input Voltage		GND		0.8	V
V_{CL}	Input Clamp Voltage	I_{CL} = −18 mA			−1.5	V
I_{IN}	Input Current	V_{IN} = 0V or 3.6V	−10	±2	+10	μA
DESERIALIZER CMOS/TTL DC SPECIFICATIONS (apply to pins $\overline{PWRDN}$, RCLK_R/$\overline{F}$, REN, REFCLK = inputs; apply to pins ROUT, RCLK, $\overline{LOCK}$ = outputs)						
V_{IH}	High Level Input Voltage		2.0		V_{CC}	V
V_{IL}	Low Level Input Voltage		GND		0.8	V
V_{CL}	Input Clamp Voltage	I_{CL} = −18 mA		−0.62	−1.5	V
I_{IN}	Input Current	V_{IN} = 0V or 3.6V	−10	±1	+10	μA
V_{OH}	High Level Output Voltage	I_{OH} = −9 mA	2.1	2.93	V_{CC}	V
V_{OL}	Low Level Output Voltage	I_{OL} = 9 mA	GND	0.33	0.6	V
I_{OS}	Output Short Circuit Current	VOUT = 0V	−15	−38	−85	mA

(1) Current into device pins is defined as positive. Current out of device pins is defined as negative. Voltages are referenced to ground except VOD, ΔVOD, VTH and VTL which are differential voltages.
(2) Typical values are given for V_{CC} = 3.3V and T_A = +25°C.

Product Folder Links: *DS92LV1021 DS92LV1210*

Electrical Characteristics[1] (continued)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ[2]	Max	Units
I_{OZ}	TRI-STATE Output Current	$\overline{PWRDN}$ or REN = 0.8V, V_{OUT} = 0V or VCC		−10	±0.4	+10	µA
SERIALIZER Bus LVDS DC SPECIFICATIONS (apply to pins DO+ and DO−)							
V_{OD}	Output Differential Voltage (DO+)–(DO−)	RL = 27Ω		200	270		mV
ΔV_{OD}	Output Differential Voltage Unbalance					35	mV
V_{OS}	Offset Voltage			0.78	1.1	1.3	V
ΔV_{OS}	Offset Voltage Unbalance					35	mV
I_{OS}	Output Short Circuit Current	D0 = 0V, DIN = High, $\overline{PWRDN}$ and DEN = 2.4V			−10	−15	mA
I_{OZ}	TRI-STATE Output Current	$\overline{PWRDN}$ or DEN = 0.8V, DO = 0V or VCC		−10	±1	+10	µA
I_{OX}	Power-Off Output Current	VCC = 0V, DO = 0V or VCC		−20	±1	+20	µA
DESERIALIZER Bus LVDS DC SPECIFICATIONS (apply to pins RI+ and RI−)							
VTH	Differential Threshold High Voltage	VCM = +1.1V			+19	+100	mV
VTL	Differential Threshold Low Voltage			−100	−7		mV
I_{IN}	Input Current	V_{IN} = +2.4V, V_{CC} = 3.6V or 0V		−10	±1	+10	µA
		V_{IN} = 0V, V_{CC} = 3.6V or 0V		−15	±1	+15	µA
SERIALIZER SUPPLY CURRENT (apply to pins DVCC and AVCC)							
I_{CCD}	Serializer Supply Current	RL = 27Ω	f = 40 MHz		32	55	mA
	Worst Case	See Figure 2	f = 16 MHz		25	45	mA
I_{CCXD}	Serializer Supply Current Powerdown	$\overline{PWRDN}$ = 0.8V			4	10	mA
DESERIALIZER SUPPLY CURRENT (apply to pins DVCC and AVCC)							
I_{CCR}	Deserializer Supply Current	C_L = 15 pF	f = 40 MHz		44	75	mA
	Worst Case	See Figure 3	f = 16 MHz		31	55	mA
I_{CCXR}	Deserializer Supply Current Powerdown	$\overline{PWRDN}$ = 0.8V, REN = 0.8V			1.5	5.0	mA

Serializer Timing Requirements for TCLK

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Units
t_{TCP}	Transmit Clock Period		25	T	62.5	ns
t_{TCIH}	Transmit Clock High Time		0.4T	0.5T	0.6T	ns
t_{TCIL}	Transmit Clock Low Time		0.4T	0.5T	0.6T	ns
t_{CLKT}	TCLK Input Transition Time			3	6	ns
t_{JIT}	TCLK Input Jitter				150	ps

(1) Typical values are given for V_{CC} = 3.3V and T_A = +25°C.

Serializer Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Units
t_{LLHT}	Bus LVDS Low-to-High Transition Time	R_L = 27Ω See Figure 4 C_L=10pF to GND		0.2	1	ns
t_{LHLT}	Bus LVDS High-to-Low Transition Time			0.25	1	ns
t_{DIS}	DIN (0-9) Setup to TCLK	See Figure 7 R_L = 27Ω, C_L=10pF to GND	1.0	0		ns
t_{DIH}	DIN (0-9) Hold from TCLK		6.5	4.5		ns

(1) Typical values are given for V_{CC} = 3.3V and T_A = +25°C.

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Serializer Switching Characteristics (continued)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Units
t_{HZD}	DO ± HIGH to TRI-STATE Delay	See Figure 8 [2] $R_L = 27\Omega$, $C_L = 10pF$ to GND		3.5	10	ns
t_{LZD}	DO ± LOW to TRI-STATE Delay			2.9	10	ns
t_{ZHD}	DO ± TRI-STATE to HIGH Delay			2.5	10	ns
t_{ZLD}	DO ± TRI-STATE to LOW Delay			2.7	10	ns
t_{SPW}	SYNC Pulse Width	See Figure 9 $R_L = 27\Omega$	$1024*t_{TCP}$		$1029*t_{TCP}$	ns
t_{PLD}	Serializer PLL Lock Time		$2048*t_{TCP}$		$2049*t_{TCP}$	ns
t_{SD}	Serializer Delay	See Figure 10 $R_L = 27\Omega$	t_{TCP}	$t_{TCP} + 2.5$	$t_{TCP} + 5$	ns
t_{BIT}	Bus LVDS Bit Width	$R_L = 27\Omega$, $C_L = 10pF$ to GND		$t_{CLK} / 12$		ns

(2) Due to TRI-STATE of the Serializer, the Deserializer will lose PLL lock and have to resynchronize before data transfer.

Deserializer Timing Requirements for REFCLK

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ[1]	Max	Units
t_{RFCP}	REFCLK Period		25	T	62.5	ns
t_{RFDC}	REFCLK Duty Cycle			50		%
t_{RFCP} / t_{TCP}	Ratio of REFCLK to TCLK Periods		0.83	1	1.03	
t_{RFTT}	REFCLK Transition Time			3	6	ns

(1) Typical values are given for $V_{CC} = 3.3V$ and $T_A = +25°C$.

Deserializer Switching Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Pin/Freq.	Min	Typ[1]	Max	Units
t_{RCP}	Receiver out Clock Period	See Figure 10 $t_{RCP} = t_{TCP}$	RCLK	25		62.5	ns
t_{CLH}	CMOS/TTL Low-to-High Transition Time	CL = 15 pF See Figure 5	Rout(0-9), LOCK, RCLK		2	5	ns
t_{CHL}	CMOS/TTL High-to-Low Transition Time				2	5	ns
t_{DD}	Deserializer Delay	See Figure 11		$1.75*t_{RCP}$	$1.75*t_{RCP}+3$	$1.75*t_{RCP}+7$	ns
t_{ROS}	ROUT (0-9) Setup Data to RCLK	See Figure 12	RCLK	$0.4*t_{RCP}$	$0.5*t_{RCP}$		ns
t_{ROH}	ROUT (0-9) Hold Data to RCLK			$-0.4*t_{RCP}$	$-0.5*t_{RCP}$		ns
t_{RDC}	RCLK Duty Cycle			40	50	60	%
t_{HZR}	HIGH to TRI-STATE Delay	See Figure 13	Rout(0-9), LOCK		$4+0.5*t_{RCP}$	$10+t_{RCP}$	ns
t_{LZR}	LOW to TRI-STATE Delay				$4.2+0.5*t_{RCP}$	$10+t_{RCP}$	ns
t_{ZHR}	TRI-STATE to HIGH Delay				$6+0.5*t_{RCP}$	$12+t_{RCP}$	ns
t_{ZLR}	TRI-STATE to LOW Delay				$6.5+0.5*t_{RCP}$	$12+t_{RCP}$	ns

(1) Typical values are given for $V_{CC} = 3.3V$ and $T_A = +25°C$.

Product Folder Links: *DS92LV1021 DS92LV1210*

Deserializer Switching Characteristics (continued)

Over recommended operating supply and temperature ranges unless otherwise specified.

Symbol	Parameter	Conditions	Pin/Freq.	Min	Typ[1]	Max	Units
t_{DSR1}	Deserializer PLL Lock Time from PWRDWN (with SYNCPAT)	See [2] See Figure 14 See Figure 15	16MHz		7	15	µs
			40MHz		4.8	25.6	µs
t_{DSR2}	Deserializer PLL Lock time from SYNCPAT		16MHz		7	10	µs
			40MHz		4.5	7	µs
t_{ZHLK}	TRI-STATE to HIGH Delay (power-up)		$\overline{LOCK}$		1.5	12	ns
t_{RNM}	Deserializer Noise Margin	See Figure 16 See [3]	16 MHz	400	1100		ps
			40 MHz	100	400		ps

(2)   For the purpose of specifying deserializer PLL performance tDSR1 and tDSR2 are specified with the REFCLK running and stable, and
      specific conditions of the incoming data stream (SYNCPATs). It is recommended that the derserializer be initialized using either tDSR1
      timing or tDSR2 timing. tDSR1 is the time required for the deserializer to indicate lock upon power-up or when leaving the power-down
      mode. Synchronization patterns should be sent to the device before initiating either condition. tDSR2 is the time required to indicate lock
      for the powered-up and enabled deserializer when the input (RI+ and RI-) conditions change from not receiving data to receiving
      synchronization patterns (SYNCPATs).
(3)   tRNM is a measure of how much phase noise (jitter) the deserializer can tolerate in the incoming data stream before bit errors occur.
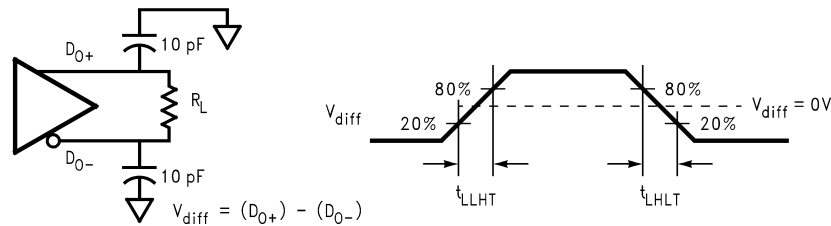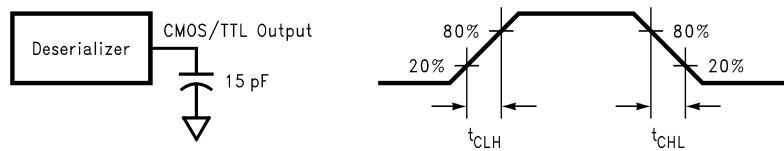
AC TIMING DIAGRAMS AND TEST CIRCUITS
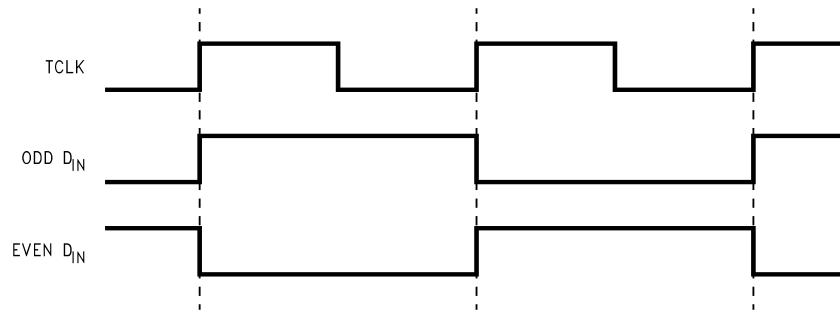
Figure 2. "Worst Case" Serializer ICC Test Pattern
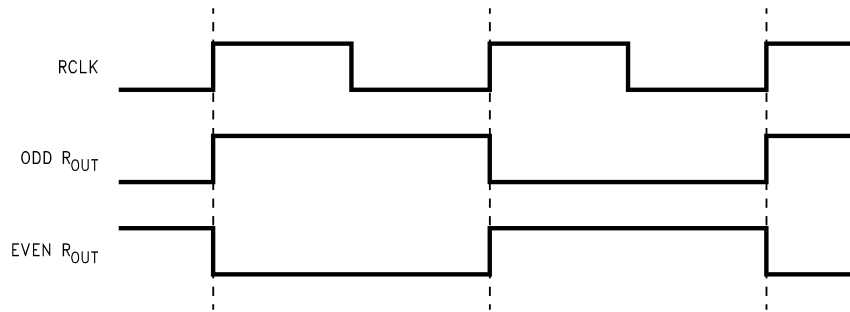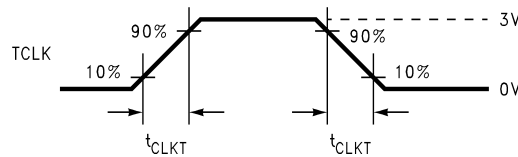

Figure 3. "Worst Case" Deserializer ICC Test Pattern

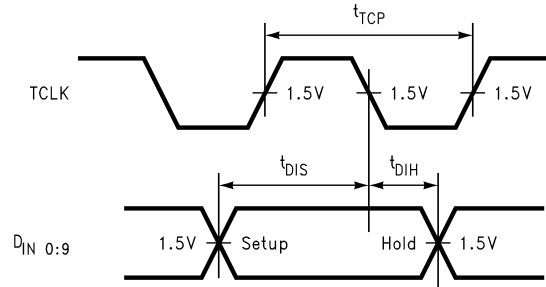**Figure 4. Serializer Bus LVDS Output Load and Transition Times**

Figure 5. Deserializer CMOS/TTL Output Load and Transition Times

Figure 6. Serializer Input Clock Transition Time

Product Folder Links: *DS92LV1021 DS92LV1210*

Timing shown for TCLK_R/$\overline{F}$ = LOW
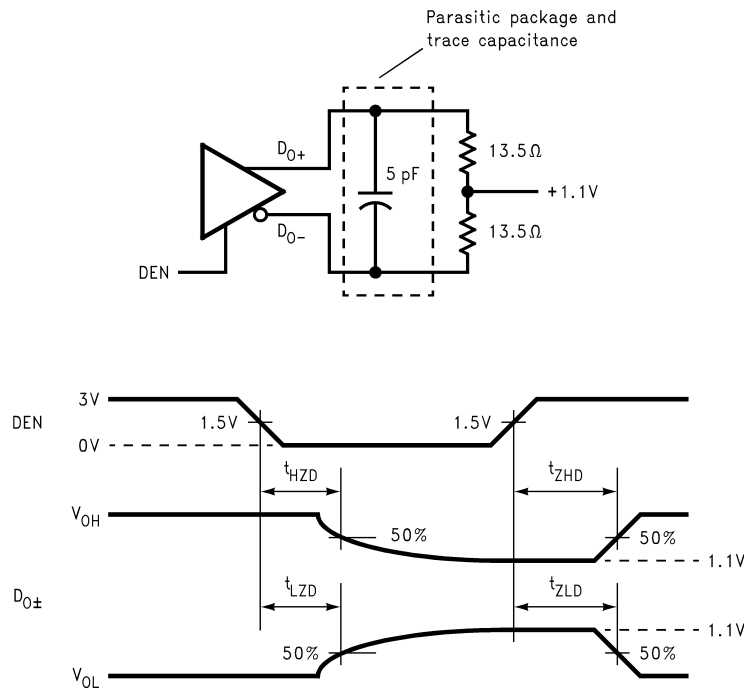
Figure 7. Serializer Setup/Hold Times

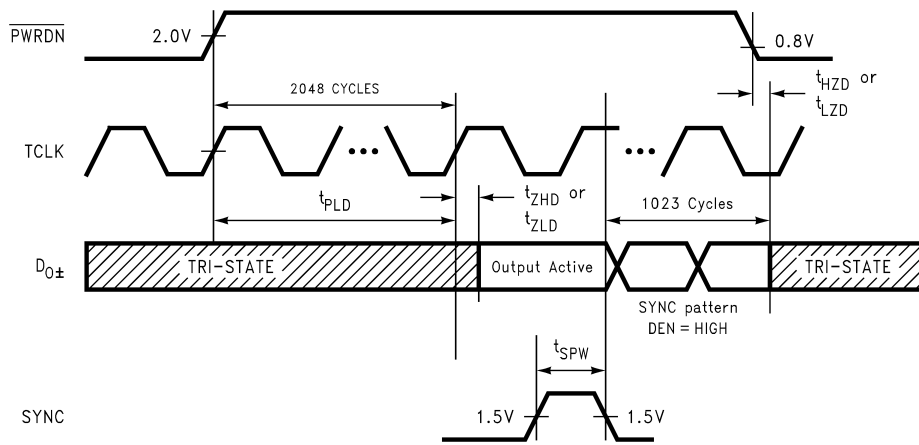**Figure 8. Serializer TRI-STATE Test Circuit and Timing**

Figure 9. Serializer PLL Lock Time, SYNC Timing and $\overline{PWRDN}$ TRI-STATE Delays

Figure 10. Serializer Delay

Figure 11. Deserializer Delay

Timing shown for RCLK_R/$\overline{F}$ = LOW

Duty Cycle (t_{RDC}) = $\dfrac{t_{HIGH}}{t_{HIGH} + t_{LOW}}$
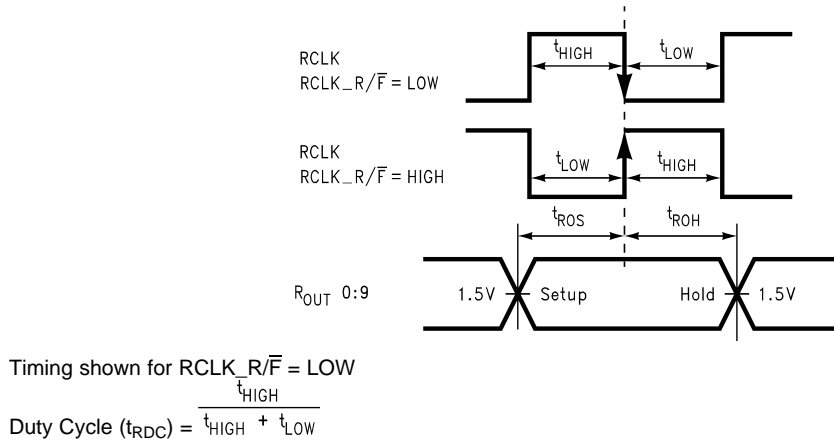
Figure 12. Deserializer Setup and Hold Times

Product Folder Links: *DS92LV1021 DS92LV1210*
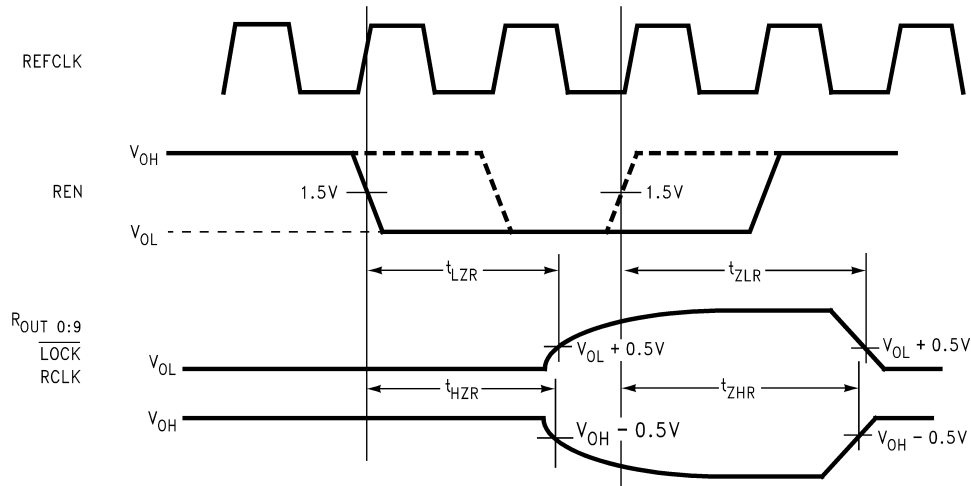
Figure 13. Deserializer TRI-STATE Test Circuit and Timing
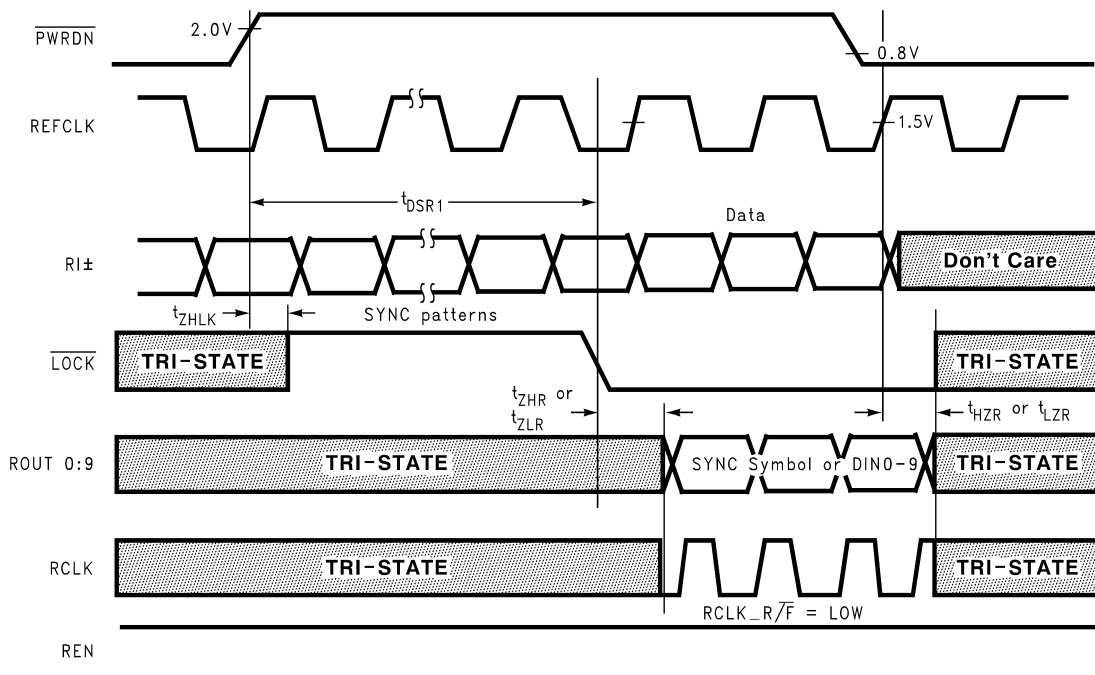
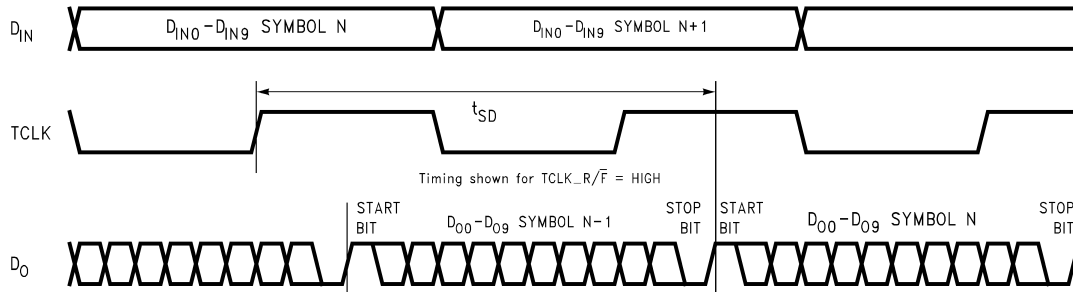**Figure 14. Deserializer PLL Lock Times and $\overline{\text{PWRDN}}$ TRI-STATE Delays**
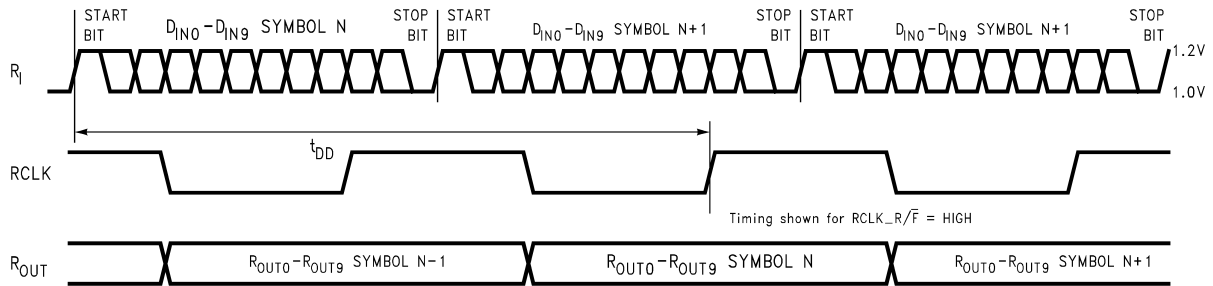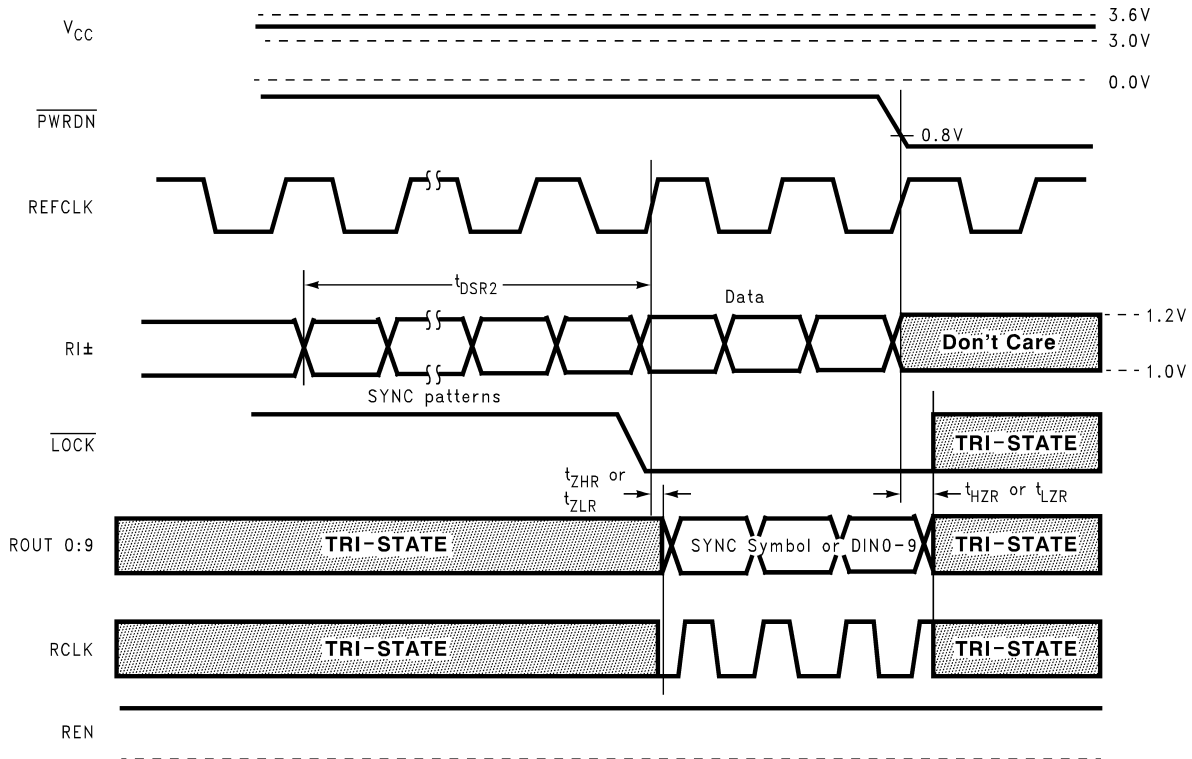
Figure 15. Deserializer PLL Lock Time from SyncPAT
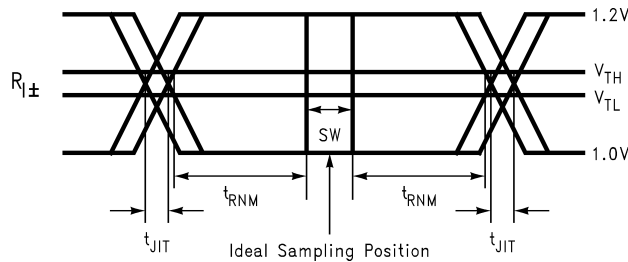
SW - Setup and Hold Time (Internal data sampling window)
t_{JIT} - Serializer Output Bit Position Jitter
t_{RSM} = Receiver Sampling Margin Time

Figure 16. Receiver Bus LVDS Input Skew Margin

$V_{OD} = (DO^+)–(DO^−)$.
Differential output signal is shown as (DO+)–(DO−), device in Data Transfer mode.

Product Folder Links: *DS92LV1021 DS92LV1210*

APPLICATION INFORMATION

USING THE DS92LV1021 AND DS92LV1210

The Serializer and Deserializer chipset is an easy to use transmitter and receiver pair that sends 10 bits of parallel TTL data over a serial Bus LVDS link up to 400 Mbps. Serialization of the input data is accomplished using an onboard PLL at the Serializer which embeds two clock bits with the data. The Deserializer uses a separate reference clock (REFCLK) a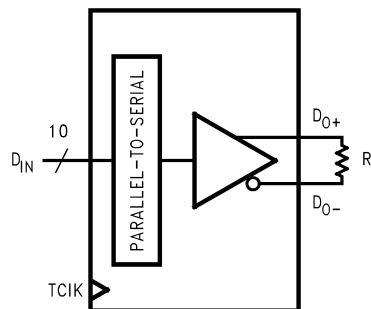nd an onboard PLL to extract the clock information from the incoming data stream and deserialize the data. The Deserializer monitors the incoming clock information to determine lock status and will indicate loss of lock by raising the $\overline{\text{LOCK}}$ output.

POWER CONSIDERATIONS

All CMOS design of the Serializer and Deserializer makes them inherently low power devices. Additionally, the constant current source nature of the Bus LVDS outputs minimize the slope of the speed vs. I_{CC} curve of CMOS designs.

POWERING UP THE SERIALIZER

The DS92LV1021 must be powered up using a specific sequence to properly start the PLL up. Not following the sequence can cause the Bus LVDS outputs to be stuck in a certain output state. This may occur if the TCLK input is driven before power is applied to the Serializer. It is important to note that this is not a latch up condition: no excessive current is drawn by the Serializer in this state and the power does not need to be cycled to recover from this state. Cycling the PWRDWN pin from high to low and back to high will reset the PLL and return the Serializer to normal operation.

To avoid this condition, the Serializer should be powered up (ALL V_{CC} pins) simultaneously with the PWRDWN pin held low for 1μs. Do not float the PWRDWN pin, external pull resistor is recommended. Once the V_{CC} pins have stabilized the TCLK input can be driven and the Serializer will be ready for data transmission.

POWERING UP THE DESERIALIZER

The DS92LV1210 can be powered up at any time following the proper sequence. The REFCLK input can be running before the Deserializer is powered up and it must be running in order for the Deserializer to lock to incoming data. The Deserializer outputs will remain in TRI-STATE until the Deserializer detects data transmission at its inputs and locks to the incoming stream. The recommended power up sequence for the deserializer is to power up all V_{CC} pins simultaneously with the PWRDWN pin held low for 1μs. Once the V_{CC} pins have stabilized the Deserializer is ready for locking. Another option to ensure proper power up is to cycle the PWRDWN pin from high to low and back to high after power up.

TRANSMITTING DATA

Once the Serializer and Deserializer are powered up and running they must be phase locked to each other in order to transmit data. Phase locking is accomplished by the Serializer sending SYNC patterns to the Deserializer. SYNC patterns are sent by the Serializer whenever SYNC1 or SYNC2 inputs are held high. The $\overline{\text{LOCK}}$ output of the Deserializer is high whenever the Deserializer is not locked. Connecting the $\overline{\text{LOCK}}$ output of the Deserializer to one of the SYNC inputs of the Serializer will ensure that enough SYNC patterns are sent to achieve Deserializer lock.

While the Deserializer $\overline{\text{LOCK}}$ output is low, data at the Deserializer outputs (ROUT0-9) is valid except for the specific case of loss of lock during transmission.

NOISE MARGIN

The Deserializer noise margin is the amount of input jitter (phase noise) that the Deserializer can tolerate and still reliably receive data. Various environmental and systematic factors include:

  Serializer: TCLK jitter, V_{CC} noise (noise bandwidth and out-of-band noise)

  Media: ISI, V_{CM} noise

  Deserializer: V_{CC} noise

RECOVERING FROM LOCK LOSS

In the case where the Serializer loses lock during data transmission up to 5 cycles of data that was previously received can be invalid. This is due to the delay in the lock detection circuit. The lock detect circuit requires that invalid clock information be received 4 times in a row to indicate loss of lock. Since clock information has been lost it is possible that data was also lost during these cycles. When the Deserializer $\overline{\text{LOCK}}$ pin goes low, data from at least the previous 5 cycles should be resent upon regaining lock.

Lock can be regained at the Deserializer by causing the Serializer to resend SYNC patterns as described above.

PCB CONSIDERATIONS

The Bus LVDS devices Serializer and Deserializer should be placed as close to the edge connector as possible. In multiple Deserializer applications, the distance from the Deserializer to the slot connector appears as a stub to the Serializer driving the backplane traces. Longer stubs lower the impedance of the bus increasing the load on the Serializer and lowers threshold margin at the Deserializers. Deserializer devices should be placed no more than 1 inch from the slot connector.

TRANSMISSION MEDIA

The Serializer and Deserializer are designed for data transmission over a multi-drop bus. Multi-drop buses use a single Serializer and multiple Deserializer devices. Since the Serializer can be driving from any point on the bus, the bus must be terminated at both ends. For example, a 100 Ohm differential bus must be terminated at each end with 100 Ohms lowering the DC impedance that the Serializer must drive to 50 Ohms. This load is further lowered by the addition of multiple Deserializers. Adding up to 20 Deserializers to the bus (depending upon spacing) will lower the total load to about 27 Ohms (54 Ohm bus). The Serializer is designed for DC loads between 27 and 100 Ohms.

The Serializer and Deserializer can also be used in point-to-point configuration of a backplane, PCB trace or through a twisted pair cable. In point-to-point configurations the transmission media need only be terminated at the receiver end. In the point-to-point configuration the potential of offsetting the ground levels of the Serializer vs. the Deserializer must be considered. Bus LVDS provides a plus / minus one volt common mode range at the receiver inputs.
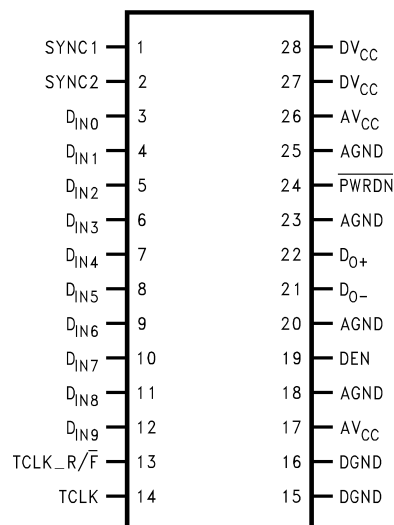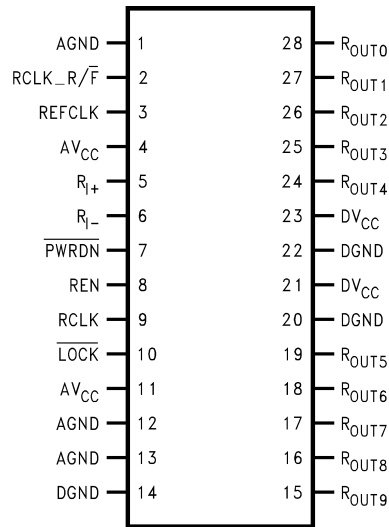
Pin Diagrams

Figure 17. DS92LV1021 Serializer DB Package

Product Folder Links: *DS92LV1021 DS92LV1210*

```
           AGND   1        28   R_OUT0
        RCLK_R/F̄  2        27   R_OUT1
          REFCLK  3        26   R_OUT2
           AV_CC  4        25   R_OUT3
             R_I+ 5        24   R_OUT4
             R_I− 6        23   DV_CC
           PWRDN  7        22   DGND
             REN  8        21   DV_CC
            RCLK  9        20   DGND
            LOCK 10        19   R_OUT5
           AV_CC 11        18   R_OUT6
            AGND 12        17   R_OUT7
            AGND 13        16   R_OUT8
            DGND 14        15   R_OUT9
```

Figure 18. DS92LV1210 Deserializer DB Package

SERIALIZER PIN DESCRIPTIONS

Pin Name	I/O	No.	Description
DIN	I	3–12	Data Input. TTL levels inputs. Data on these pins are loaded into a 10-bit input register.
TCLK_R/$\overline{F}$	I	13	Transmit Clock Rising/Falling strobe select. TTL level input. Selects TCLK active edge for strobing of DIN data. High selects rising edge. Low selects falling edge.
DO+	O	22	+ Serial Data Output. Non-inverting Bus LVDS differential output.
DO−	O	21	− Serial Data Output. Inverting Bus LVDS differential output.
DEN	I	19	Serial Data Output Enable. TTL level input. A low, puts the Bus LVDS outputs in TRI-STATE.
$\overline{PWRDN}$	I	24	Powerdown. TTL level input. $\overline{PWRDN}$ driven low shuts down the PLL and TRI-STATEs outputs putting the device into a low power sleep mode. Do not float the PWRDWN pin, external pull resistor is recommended. A pull-down will disable the device until it is actively driven (enabled).
TCLK	I	14	Transmit Clock. TTL level input. Input for 16 MHz–40 MHz (nominal) system clock.
SYNC	I	1, 2	Assertion of SYNC (high) for at least 1024 synchronization symbols to be transmitted on the Bus LVDS serial output. Synchronization symbols continue to be sent if SYNC continues asserted. TTL level input. The two SYNC pins are ORed.
DVCC	I	27, 28	Digital Circuit power supply.
DGND	I	15, 16	Digital Circuit ground.
AVCC	I	17, 26	Analog power supply (PLL and Analog Circuits).
AGND	I	18, 25, 20, 23	Analog ground (PLL and Analog Circuits).

DESERIALIZER PIN DESCRIPTION

Pin Name	I/O	No.	Description
ROUT	O	15–19, 24–28	Data Output. ±9 mA CMOS level outputs.
RCLK_R/$\overline{F}$	I	2	Recovered Clock Rising/Falling strobe select. TTL level input. Selects RCLK active edge for strobing of ROUT data. High selects rising edge. Low selects falling edge.
RI+	I	5	+ Serial Data Input. Non-inverting Bus LVDS differential input.
RI−	I	6	− Serial Data Input. Inverting Bus LVDS differential input.

DESERIALIZER PIN DESCRIPTION (continued)

Pin Name	I/O	No.	Description
$\overline{PWRDN}$	I	7	Powerdown. TTL level input. $\overline{PWRDN}$ driven low shuts down the PLL and TRI-STATEs outputs putting the device into a low power sleep mode.
$\overline{LOCK}$	O	10	$\overline{LOCK}$ goes low when the Deserializer PLL locks onto the embedded clock edge. CMOS level output. Totem pole output structure, does not directly support wire OR connection.
RCLK	O	9	Recovered Clock. Parallel data rate clock recovered from embedded clock. Used to strobe ROUT, CMOS level output.
REN	I	8	Output Enable. TTL level input. TRI-STATEs ROUT0–ROUT9, $\overline{LOCK}$ and RCLK when driven low.
DVCC	I	21, 23	Digital Circuit power supply.
DGND	I	14, 20, 22	Digital Circuit ground.
AVCC	I	4, 11	Analog power supply (PLL and Analog Circuits).
AGND	I	1, 12, 13	Analog ground (PLL and Analog Circuits).
REFCLK	I	3	Use this pin to supply a REFCLK signal for the internal PLL frequency.

Truth Table

DIN (0–9)	TCLK_R/$\overline{F}$	TCLK	SYNC1/SYNC2	DEN	$\overline{PWRDN}$	DO+	DO−	
X	X	X	X	X	0	Z	Z	
X	X	X	X	0	1	Z	Z	
X	X	SYSTEM CLK	1[1]	1	1	SYNC PTRN	SYNC PTRN[2]	
DATA	1		0	1	1	DATA (0–9)	DATA (0–9)v	
DATA	0		0	1	1	DATA (0–9)	DATA (0–9)[2]	
RI	RI−	RCLK_R/$\overline{F}$	REFCLK	REN	$\overline{PWRDN}$	RCLK	$\overline{LOCK}$	ROUT (0–9)
X	X	X	X	X	0	Z	Z	Z
X	X	X	X	0[3]	1	Z	Z	Z
SYNC PTRN	SYNC PTRN[2]	X	SYSTEM CLK	1	1	CLK	1[4]	SYNC PTRN
DATA (0–9)	DATA (0–9)[2]	1	SYSTEM CLK	1	1		0	DATA
DATA (0–9)	DATA (0–9)[2]	0	SYSTEM CLK	1	1		0	DATA

(1) Pulse 5-bits
(2) Inverted
(3) Device must be locked first
(4) Must be 1 before SYNC PTRN starts

REVISION HISTORY

Changes from Revision B (April 2013) to Revision C   **Page**

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DS92LV1021TMSA	NRND	SSOP	DB	28	47	TBD	Call TI	Call TI		DS92LV1021T MSA	
DS92LV1021TMSA/NOPB	NRND	SSOP	DB	28	47	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		DS92LV1021T MSA	
DS92LV1021TMSAX	OBSOLETE	SSOP	DB	28		TBD	Call TI	Call TI		DS92LV1021T MSA	
DS92LV1021TMSAX/NOPB	NRND	SSOP	DB	28	2000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR		DS92LV1021T MSA	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
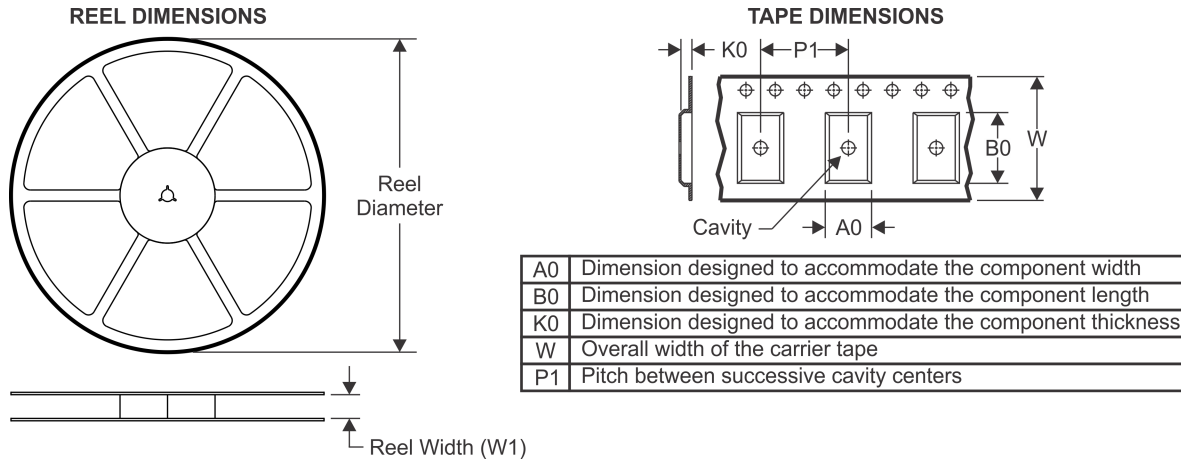
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

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![Texas Instruments logo] **PACKAGE MATERIALS INFORMATION**

TAPE AND REEL INFORMATION

REEL DIMENSIONS

Reel Diameter

Reel Width (W1)

TAPE DIMENSIONS

Cavity

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Sprocket Holes

User Direction of Feed

Pocket Quadrants

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS92LV1021TMSAX/NOPB	SSOP	DB	28	2000	330.0	16.4	8.4	10.7	2.4	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS92LV1021TMSAX/NOPB	SSOP	DB	28	2000	367.0	367.0	38.0

DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
         B. This drawing is subject to change without notice.
         C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
         D. Falls within JEDEC MO-150

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